IN RE APPLICATION OF: Tsutomu SATO et al.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

GAU:

SERIAL NO: New Application	EXAMINER:
FILED: Herewith	
SUBSTRATE WITH ON	EVICE FORMED IN SEMICONDUCTOR LAYER ARRANGED ON NE OF INSULATING FILM AND CAVITY INTERPOSED BETWEEN THE E SEMICONDUCTOR LAYER
REQUEST FOR PRIORITY	
COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313	
SIR:	
Full benefit of the filing date of U. pursuant to the provisions of 35 U.	S. Application Serial Number 10/091,448, filed March 7, 2002, is claimed S.C. §120.
☐ Full benefit of the filing date(s) of §119(e):	U.S. Provisional Application(s) is claimed pursuant to the provisions of 35 U.S.C. <u>Application No.</u> <u>Date Filed</u>
Applicants claim any right to priority from any earlier filed applications to which they may be entitled pursuant to the provisions of 35 U.S.C. §119, as noted below.	
In the matter of the above-identified application for patent, notice is hereby given that the applicants claim as priority:	
COUNTRY Japan	APPLICATION NUMBER 2001-398184 MONTH/DAY/YEAR December 27, 2001
Certified copy of the corresponding Co	envention Application(s)
☐ will be submitted prior to paym	ent of the Final Fee
was filed in prior application Serial No. 10/091,448 filed March 7, 2002	
□ were submitted to the International Bureau in PCT Application Number Receipt of the certified copies by the International Bureau in a timely manner under PCT Rule 17.1(a) has been acknowledged as evidenced by the attached PCT/IB/304.	
☐ (A) Application Serial No.(s) w	vere filed in prior application Serial No. filed ; and
☐ (B) Application Serial No.(s)	
are submitted herewith	
□ will be submitted prior to payment of the Final Fee	
	Respectfully Submitted,
	OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.
22850	Thhund Huesten
Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03) I:\ATTY\RFF\24\$\241280\241280-NEW-PRIORITY.	Eckhard H. Kuesters Registration No. 28,870